

# SN54HC132-DIE 四路正与非 (NAND) 门, 具有施密特触发器输入

## 1 特性

- 宽工作电压范围
- 低功耗
- 低输入电流
- 极低输入转换运行
- 高抗扰度

## 2 应用范围

- 手机
- 掌上电脑 (PDA)
- 便携式仪表
- 音频和视频信号路由
- 低压数据采集系统
- 通信电路
- 调制解调器
- 硬盘
- 计算机外设
- 无线终端和外设

## 3 说明

这个电路的功能为 **NAND** 门, 但是由于施密特操作, 它对于正向和负向信号有不同的输入阀值电平。

**SN54HC132-DIE** 在正逻辑电路中执行布尔函数

$$Y = \overline{A \bullet B} \text{ 或 } Y = \overline{A} + \overline{B}.$$

这个电路是温度补偿电路, 可由输入斜坡的最低点触发, 并且仍然能够提供清洁的无抖动输出信号。

## Ordering Information<sup>(1)</sup>

PRODUCT	PACKAGE DESIGNATOR	PACKAGE	ORDERABLE PART NUMBER	PACKAGE QUANTITY
SN54HC132	TD	Bare die in waffle pack <sup>(2)</sup>	SN54HC132TDG1	154
			SN54HC132TDG2	10

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).

(2) Processing is per the Texas Instruments commercial production baseline and is in compliance with the Texas Instruments Quality Control System in effect at the time of manufacture. Electrical screening consists of DC parametric and functional testing at room temperature only. Unless otherwise specified by Texas Instruments AC performance and performance over temperature is not warranted. Visual Inspection is performed in accordance with MIL-STD-883 Test Method 2010 Condition B at 75X minimum.



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

English Data Sheet: [SCLS750](http://SCLS750)



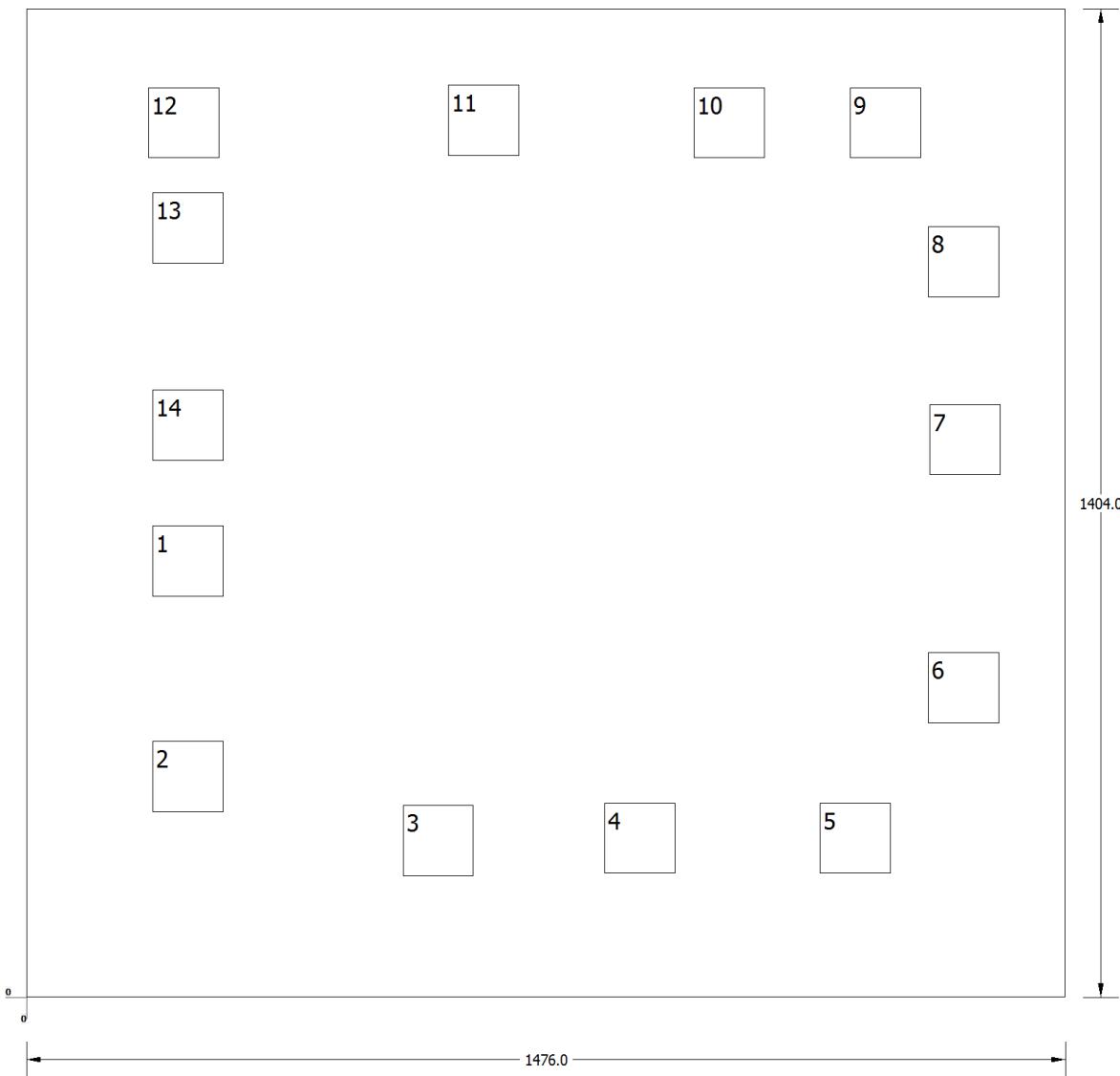
This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.



ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## 4 Bare Die Information

DIE THICKNESS	BACKSIDE FINISH	BACKSIDE POTENTIAL	BOND PAD METALLIZATION COMPOSITION	BOND PAD THICKNESS
10.5 mils.	Silicon with backgrind	Floating	TiW/ALCu2%	1210 nm



**Bond Pad Coordinates in Microns**

DESCRIPTION	PAD NUMBER	X MIN	Y MIN	X MAX	Y MAX
1A	1	179.1	568.8	279.9	669.6
1B	2	179.1	262.8	279.9	363.6
1Y	3	534.6	171.9	635.4	272.7
2A	4	821.25	175.5	922.05	276.3
2B	5	1127.25	175.5	1228.05	276.3
2Y	6	1280.7	388.8	1381.5	489.6
GND	7	1282.95	741.6	1383.75	842.4
3Y	8	1280.7	994.5	1381.5	1095.3
3A	9	1170.45	1191.6	1271.25	1292.4
3B	10	948.15	1191.6	1048.95	1292.4
4Y	11	598.95	1195.2	699.75	1296
4A	12	172.8	1191.6	273.6	1292.4
4B	13	179.1	1042.2	279.9	1143
VCC	14	179.1	762.3	279.9	863.1

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN54HC132TDG1	ACTIVE			0	100	RoHS & Green	Call TI	N / A for Pkg Type	25 to 25		Samples
SN54HC132TDG2	ACTIVE			0	10	RoHS & Green	Call TI	N / A for Pkg Type	25 to 25		Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54HC132-DIE :**

- Space : [SN54HC132-SP](#)

NOTE: Qualified Version Definitions:

- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

## 重要声明和免责声明

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